US00D729753S

(12) **United States Design Patent**
Fukushima et al.

(10) **Patent No.:** **US D729,753 S**
(45) **Date of Patent:** ** **May 19, 2015**

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(54) **ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING**

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(73) Assignee: **Ebara Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/496,207**

(22) Filed: **Jul. 10, 2014**

Related U.S. Application Data

(62) Division of application No. 29/384,219, filed on Jan. 28, 2011, now Pat. No. Des. 711,330.

(30) **Foreign Application Priority Data**

Dec. 28, 2010 (JP) 2010-031213
Dec. 28, 2010 (JP) 2010-031214
Dec. 28, 2010 (JP) 2010-031215
Dec. 28, 2010 (JP) 2010-031216

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
CPC B24B 37/30; B24B 41/061; B24B 49/16
USPC D13/182; 451/66, 288, 289
See application file for complete search history.

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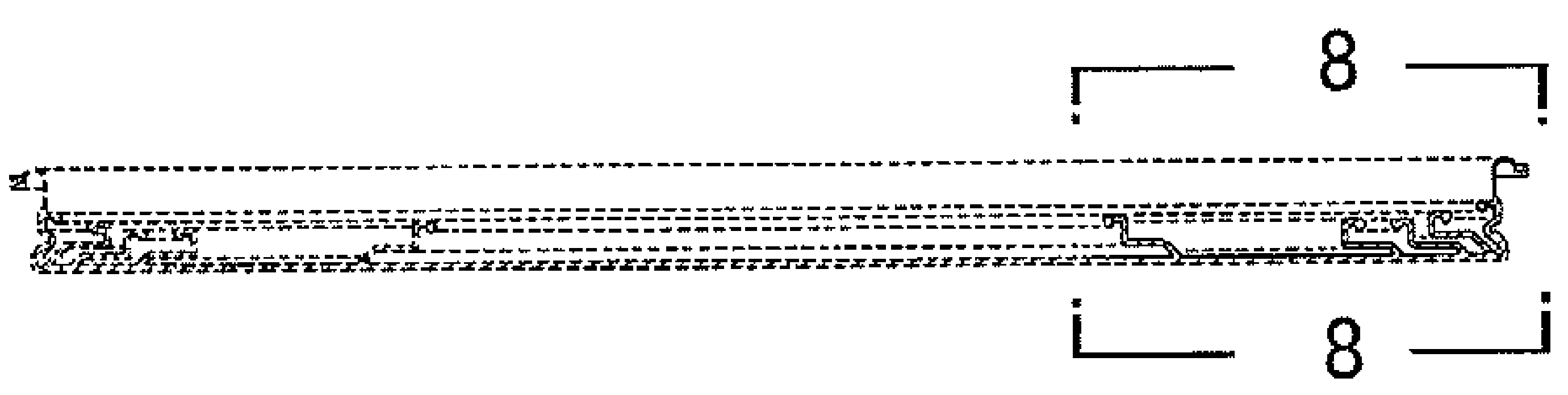
(57) **CLAIM**

The ornamental design for an elastic membrane for semiconductor wafer polishing, as shown and described.

DESCRIPTION

FIG. **1** is a front view of an elastic membrane for semiconductor wafer polishing showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a bottom view thereof;
FIG. **4** is a plan view thereof;
FIG. **5** is a left side view thereof;
FIG. **6** is a right side view thereof;
FIG. **7** is a cross-section view taken along the line **7**-**7** of FIG. **2** thereof;
FIG. **8** is a enlarged view of part **8** of FIG. **7** thereof; and,
FIG. **9** is a enlarged perspective view, observed from above thereof.
The broken lines depict environmental subject matter only and form no part of the claimed design.

1 Claim, 3 Drawing Sheets



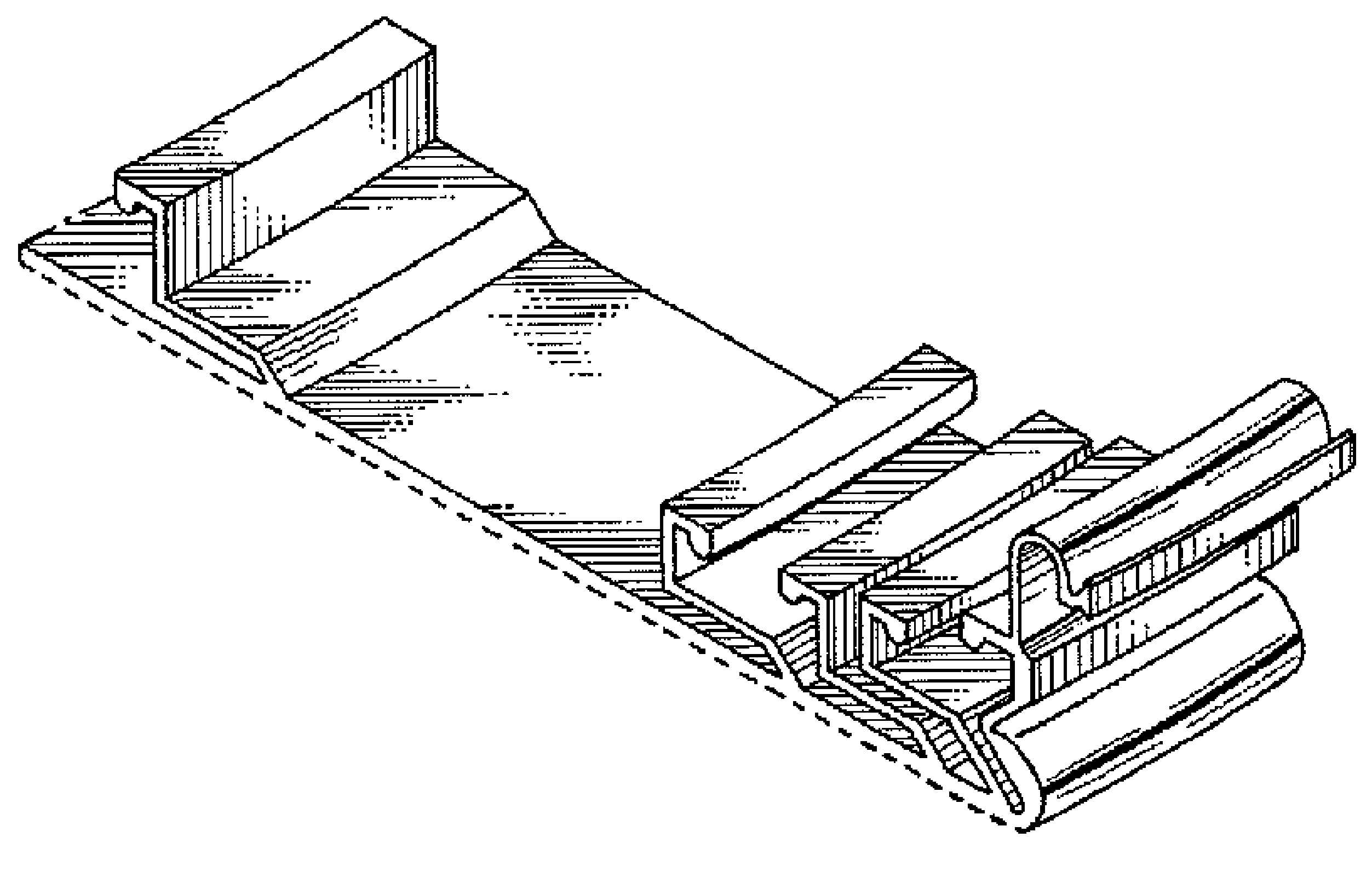


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FIG. 1

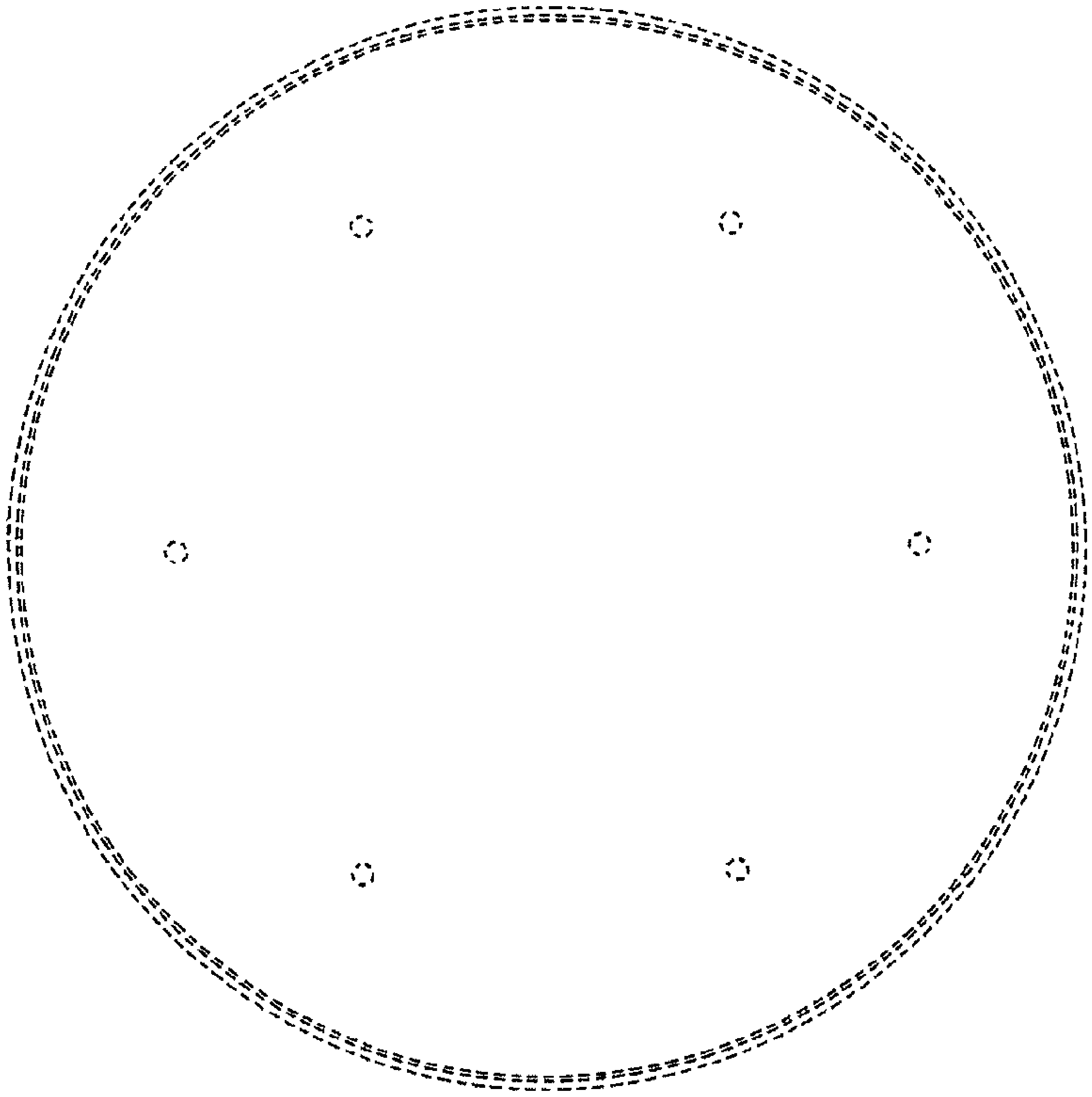

FIG. 2

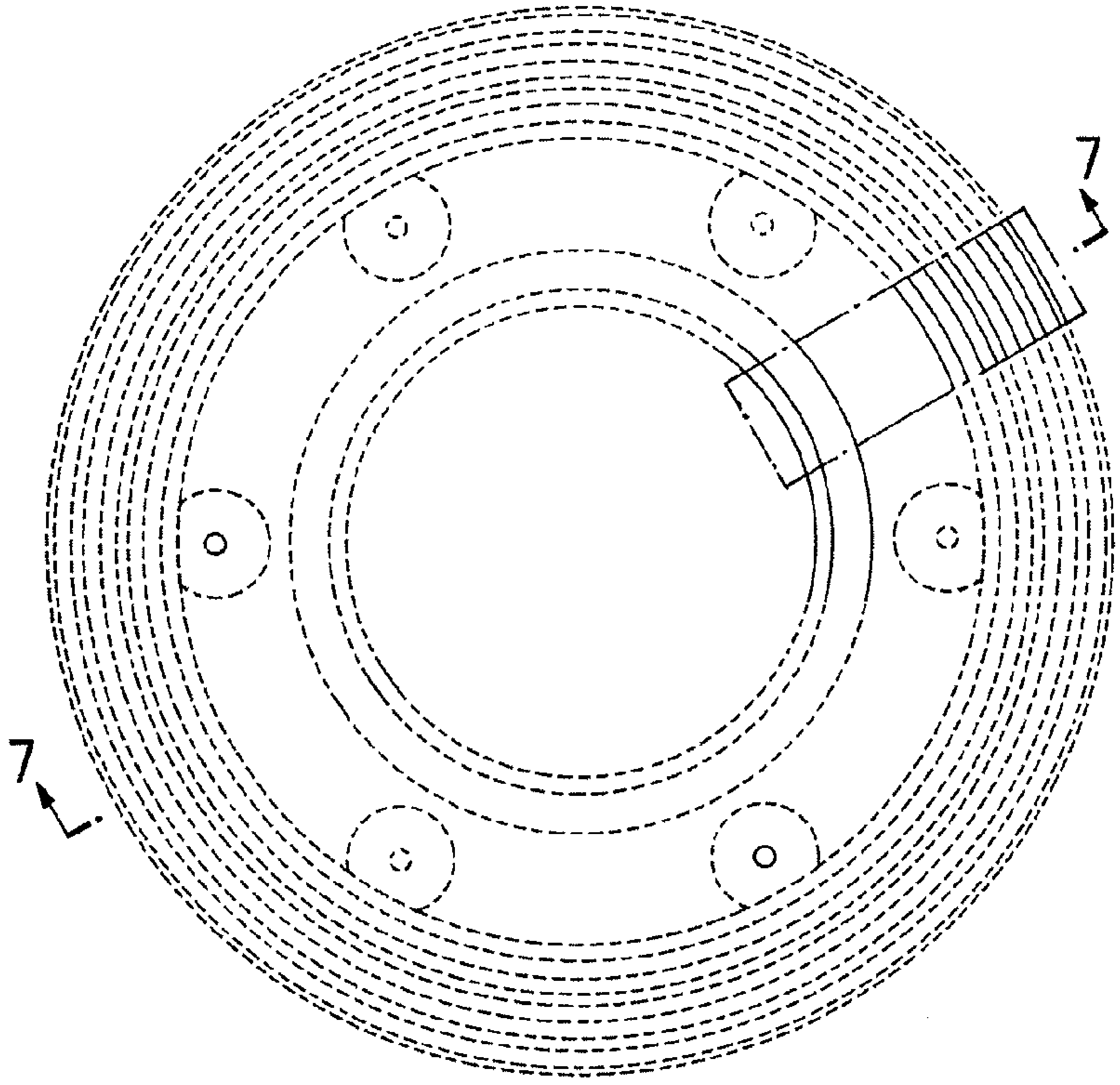

FIG. 3

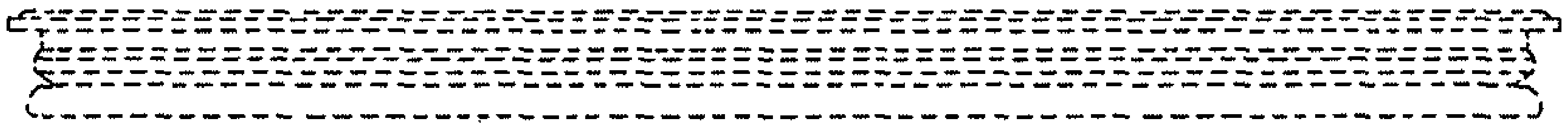

FIG. 4

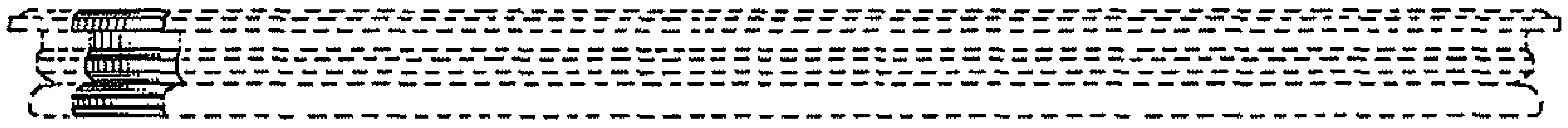

FIG. 5

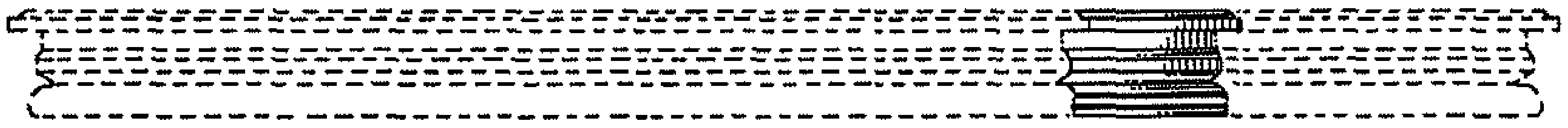

FIG. 6

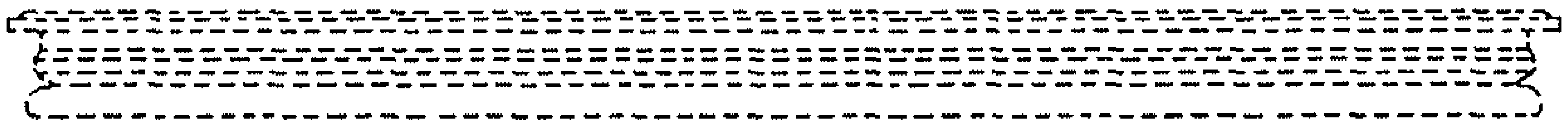

FIG. 7

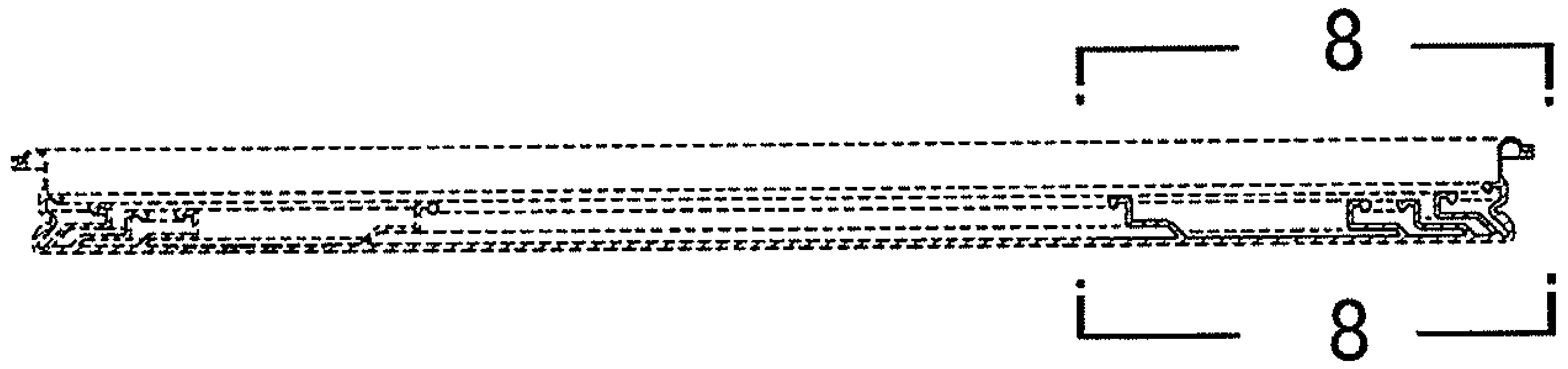

FIG. 8

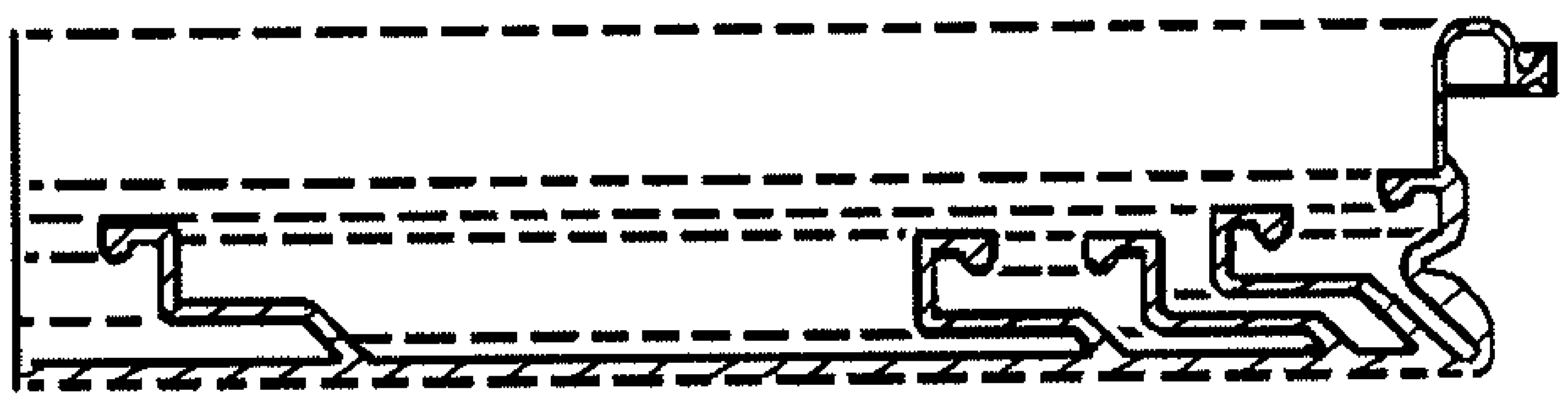

FIG. 9